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(54) HERMETIC FEEDTHROUGH FOR AN IMPLANTABLE DEVICE

HERMETISCHE DURCHFÜHRUNG FÜR EINE IMPLANTIERBARE VORRICHTUNG

PASSAGE HERMETIQUE POUR DISPOSITIF IMPLANTABLE

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(56) References cited:
US-A- 4 650 922 **US-A- 5 193 539**
US-A- 5 293 069 **US-A- 5 750 926**

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Description

Field of the Invention

[0001] The present invention is generally directed to an implantable medical device, e.g., an implantable sensor, and in particular is related to techniques for providing hermetic connections to such a device.

Background of the Invention

[0002] The present invention relates to semiconductor substrates, and more particularly to a semiconductor substrate fabricated to include hermetically-sealed electronic circuitry as well as non-hermetically-sealed electrodes thereon so as to form an implantable sensor or other implantable electronic device.

[0003] In U.S. Patent No. 5,660,163 (hereafter the '163 patent), there is disclosed an implantable glucose sensor which is fabricated on a ceramic substrate. Working electrodes and other elements associated with the sensor are exposed to a conductive fluid contained within a reservoir or inner sheath that covers the substrate. An outer sheath is also placed over the sensor, with a window formed over one of the working electrodes. A selected enzyme, such as glucose oxidate (GO), is placed within the window. As disclosed in the '163 patent, five wires or conductors are attached to the electrodes and connected to electronic circuitry, e.g., a circuit such as is shown in **FIG. 3** of the '163 patent.

[0004] Additional features, aspects and improvements of a glucose sensor of the type disclosed in the '163 patent are further disclosed in U.S. Patent No. 6,081,736; U.S. Patent No. 6,119,028; U.S. Patent No. 5,999,848.

[0005] As disclosed in the referenced patents, an improved implantable sensor may be fabricated by placing the electrodes on one side of the substrate and by also placing an integrated circuit (IC) chip on the other side of the substrate, along with other needed electronic components, e.g., a capacitor(s), thereby forming a hybrid electronic circuit on the side of the substrate opposite the electrodes that is used to control or drive the sensor. The sensor senses the electrical current flowing to the electrodes, from which current the amount of oxygen near the electrodes can be determined, from which oxygen level determination, the amount of glucose to which the sensor is exposed can also be determined. Additional, the sensor sends and receives information, data, and/or power from an external location over a two-conductor transmission line. The IC chip and other electronic components are hermetically sealed under a metal cover, the edges of which are hermetically bonded to the substrate. Electrical connection is established with the IC chip and other sealed components through stair-step vias or passageways that traverse through the substrate. Several of these types of sensors may be daisy-chained together, using just two conductors, as required. The outer sheath encircles the entire substrate, both the electronic circuit side with its metal cover, and the sensor electrode side, with its electrodes, saline solution reservoir and enzyme-filled window.

[0006] Disadvantageously, the sensor described in the referenced patents and patent applications is relatively thick. For many implantable applications, a thinner sensor is needed that still provides hermetic electrical connections to its internal circuitry. Hence, there remains a need for yet a smaller sensor that performs all of the same functions as the prior sensor, i.e., that provides working electrodes exposed to a saline, with a selected enzyme placed over one electrode, and with hermetically-sealed electronic circuitry controlling the sensor and communicating with other sensors and an external control unit. The present invention advantageously addresses these and other needs.

[0007] According to a first aspect of the present invention there is provided a hermetically sealed package suitable for implantation in living tissue, said package being defined in claim 1.

[0008] According to a second aspect of the present invention there is provided a method of forming an electrically conductive hermetic connection to a hermetically sealed integrated circuit, said method being defined in claim 11.

[0009] The present invention provides an implantable substrate sensor wherein electronic circuitry associated with the sensor, i.e., the IC chip, is formed within, or on, a suitable substrate, e.g., a CMOS substrate. A protective coating then covers the substrate, effectively forming a hermetically sealed package having the circuitry under the coating. In embodiments of the present invention, the circuitry has one or more electrically conductive pads for communicating and/or providing power to the circuitry. One or more electrical pathways provide hermetic electrical connection to the conductive pads for external connection to the sealed circuitry within the sealed package. Electrodes associated with the sensor may be selectively left uncovered by the protective coating, thereby allowing such electrodes to be exposed to body tissue and fluids when the sensor is implanted in living tissue.

[0010] In a first embodiment, the electrical pathway is a via that is made from a biocompatible material, e.g., platinum, that is made hermetic by either increasing its thickness, e.g., to at least 5 microns, or by ion beam deposition. The electrical pathways are formed from metal traces essentially parallel to the surface of the substrate that are connected at their first ends by first vias to conductive pads on the circuitry and with their second ends extending external to the sealed package, thus providing external electrical connection to the hermetically sealed circuitry. The metal traces are surrounded by a biocompatible insulation material, e.g., alumina, zirconia, or alloys of alumina and zirconia. Due to this combination of vias and metal traces surrounded by insulation material, the resulting electrical connection is hermetic.

[0011] In accordance with one aspect of the invention, a pair of thin substrate sensors made in accordance with

the present invention, each having electronic circuitry formed on one side of the substrate may be placed back-to-back with the interconnecting and/or sensing electrodes facing outward. Such a back-to-back pair of substrate sensors advantageously allows the sensor electrodes to be positioned on the outside surfaces of the sensor pair substrates.

[0012] A hermetically sealed package suitable for implantation in living tissue comprises (1) a semiconductor substrate having a plurality of surfaces and having an integrated circuit formed on at least one of said surfaces, the integrated circuit having one or more electrically conductive pads for communicating and/or providing power to the integrated circuit, (2) one or more electrical pathways for providing electrical connection to the one or more electrically conductive pads, the pathways having first ends coupled to the one or more pads and second ends exposed for external electrical connection from the sealed package, and (3) an insulating material for encapsulating the integrated circuit and the semiconductor substrate surfaces except for selected portions of the second ends of the electrical pathways.

[0013] The novel features of the invention arc set forth with particularity in the appended claims. The invention will be best understood from the following description when read in conjunction with the accompanying drawings.

[0014] US-A-5,782,891 describes an implantable medical device with a ceramic enclosure having a multilayered ceramic feedthrough substrate.

[0015] US-A-5,833,603 describes a bio sensing transponder for implantation into an organism. A control circuit (an integrated circuit) is mounted on a substrate and supports an energy coupler. A capsule protects the circuit and coupler. Electrodes may protrude through a wall of the capsule and may be sealed thereto to form hermetic feedthroughs.

[0016] US-A-6,043,437 describes an implantable sensor consisting of a hybrid circuit formed on an insulating substrate. A further insulation coating layer made of alumina is provided to encapsulate the substrate and the hybrid circuit so that only the essential electrical contacts are accessible from outside the sensor. Conductive pathways are provided between the hybrid circuit and the external contact in the form of a coated wire.

Brief Description of the Drawings

[0017] The above and other aspects, features and advantages of the present invention will be more apparent from the following more particular description thereof, presented in conjunction with the following drawings.

FIG. 1 is a block diagram that illustrates multiple sensors/stimulators connected together using a two-conductor bus, which two-conductor bus may be connected to a controller.

FIG. 2 schematically illustrates a preferred manner of how a sensor/stimulator may be connected with a controller and other sensors/stimulators in a serial or daisy-chain fashion.

FIG. 3A shows a perspective, partially exploded, view of a sensor/stimulator of the type disclosed in the referenced patent application as used in the daisy chain of **FIG. 2.**

FIG. 3B illustrates a sectional side view of the sensor/stimulator of **FIG. 3A.**

FIG. 3C illustrates a sectional top view of the sensor/stimulator of **FIG. 3A.**

FIG. 3D illustrates a sectional end view of the sensor/stimulator of **FIG. 3A.**

FIG. 4 depicts an implantable lead that includes a plurality of the sensor/stimulators of **FIGS. 3A-3D.**

FIGS. 5A and **5B** respectively shows perspective and cross sectional views of a sensor not in accordance with the present invention, which provides a hermetic electrical connection to a semiconductor formed on the substrate by enhancing the hermeticity of the electrically conductive via.

FIGS. 6A and **6B** respectively shows a perspective and a cross sectional view of an embodiment of a preferred sensor substrate made in accordance with the present invention, which provides a hermetic connection to a semiconductor formed on substrate by forming a combination of via and metallic pathways surrounded by an insulating material.

FIG. 7 shows a partial cross section of a next alternative embodiment of a technique for providing a hermetic electrical connection to the semiconductor formed on the substrate.

FIG. 8 shows one method that may be used to deposit a protective coating or layer over the sensor substrate.

FIG. 9 illustrates a sensor assembly formed by placing two sensor substrates back-to-back so that the electrodes of both sensor substrates face outwardly from the assembly.

FIG. 10 depicts use of the sensor assembly of **FIG. 9** within a sheath and membrane to form an electrochemical sensor assembly.

[0018] Corresponding reference characters indicate corresponding components throughout the several views of the drawings.

Detailed Description of the Preferred Embodiments

[0019] At the outset, it is to be noted that implantable sensors are generally used to sense some type of physiological parameter or condition or other event that occurs within, or is sensible from a location within, living tissue of a patient. To that end, such sensors employ one or more electrodes, or similar transducers, that convert a sensed parameter to an electrical or other detectable signal. Ofttimes, a sensor simply senses an electro-potential signal, such as that which typically accompanies depo-

larization of muscle tissue, or other natural electrical signals associated with the patient's body. In such an instance, all the sensor need employ is some type of electrode that is in contact with the monitored tissue and appropriate electronic circuitry for receiving, amplifying and/or storing any signal that is sensed. Also, it is common to employ the electrode of such sensor as a stimulator as well, through which an electrical current pulse may be applied to tissue in contact with the electrode. Thus, it is common to refer to a sensor electrode, which also may be used as a stimulus electrode, as a sensor/stimulator. Further, the sensor may be used as an electrochemical sensor, or enzyme electrode sensor, e.g., of the type disclosed in the '163 patent or the other referenced patents. For such an electrochemical sensor, a suitable enzyme or other chemical is placed in close proximity to the electrodes so that the desired chemical interactions may take place.

[0020] Whatever the type of implantable sensor employed, a common element(s) in all such sensors is the electrode and the electronic circuitry used to monitor and/or control the electrode(s). It is to be understood, however, that other sensor elements, e.g., an enzyme, may be used in conjunction with the electrode and associated electronic circuitry.

[0021] To better understand and appreciate the advantages offered by the present invention, it will first be helpful to briefly review a preferred application and manner of making an implantable sensor of the type disclosed in the referenced patent and patent applications. To that end, reference is made to **FIG. 1,** where there is shown a block diagram that illustrates multiple sensor/stimulators 12a, 12b, ... 12n, connected together, as well as to a controller (not shown) using just two common conductors 14 and 16. The two conductors 14 and 16 provide a common signal and return for data signals and power signals that are sent from the controller to the sensor/stimulators 12a, 12b, ... 12n, as well as a common signal and return path for data signals transmitted from the sensor/stimulators 12a, 12b, ... 12n, to the controller.

[0022] **FIG. 2** schematically illustrates how an implantable device, e.g., a sensor/stimulator 18a, may be connected with a remote controller 20 and other implantable sensor/stimulators 18b, ... 18n, in a serial or daisy-chain fashion. As seen in **FIG. 2,** the sensor/stimulator 18a is connected to the controller 20 by two conductors 14' and 16' which are attached to a first pair of pads or terminals 13 and 15 along a proximal side (i.e., the side closest to the controller 20) of the sensor/stimulator 18a. Another pair of pads or terminals 17 and 19 are located along a distal side (i.e., the side farthest from the controller 20) of the sensor/stimulator 18a. As will become evident from the description that follows, the distal pad 17 is electrically connected to the proximal pad 13 through the circuitry 21 located on the sensor/stimulator 18a. Similarly, the distal pad 19 is electrically connected to the proximal pad 15 through the circuitry 21 included within the sensor/stimulator 18a. Two additional conductors 14" and 16" are then used to connect the distal pads 17 and 19 of the device 18a to corresponding proximal pads 13' and 15' of the next sensor/stimulator 18b connected in the daisy chain. In this manner, as many devices as desired may be serially connected to the controller 20 using just two conductors.

[0023] It is noted that **FIG. 1** is functionally electrically equivalent to **FIG. 2. FIG. 2** simply employs proximal and distal pairs of pads or terminals to facilitate the connection of additional devices to the chain by extending two conductors from the distal pads 17 and 19 of a more proximal device in the chain to the proximal pads 13' and 15' of a new device to be added to the chain. However, where the particular application allows connections to be made to, or branched off of, the two main conductors 14 and 16, then the configuration of **FIG.** 1 may be used just as well as the configuration of **FIG. 2.**

[0024] There exist many different applications for the daisy-chainable sensor/stimulators 12 or 18 of the system illustrated in **FIGS. 1** or **2.** Generally, where the sensor/stimulators 12 or 18 are implanted, they are designed to sense one or more body parameters or substances found in body tissue or fluids, e.g., glucose level, blood pH, O_2, temperature, or the like. Such measurements can provide valuable information regarding the condition and status of the patient. As such, it is ofttimes desirable to make more than one measurement within the same general body tissue area so as to be able to compute an average or mean of the measurements thus made or otherwise obtain a consensus from several different readings, thereby better assuring the accuracy and reliability of the data thus gathered.

[0025] Other times, it may be desirable to obtain various measurements of a given substance at physically related, but different, body locations. For example, for some applications, e.g., a closed-loop insulin infusion system, it could be advantageous to obtain a glucose reading within the blood stream and another glucose reading within the blood stream and another glucose reading within the body tissue adjacent the blood stream. This is because the time constant associated with how readily one glucose reading changes compared with the other may be different (and, in fact, is usually different), and being able to obtain or monitor such difference would provide valuable information regarding the regulation of the insulin infusion.

[0026] Turning next to **FIGS. 3A, 3B, 3C** and **3D,** there are shown, respectively, a perspective exploded view **(FIG. 3A),** a side view **(FIG. 3B),** a top view **(FIG. 3C),** and an end view **(FIG. 3D),** of a typical implantable sensor device 30 of the type disclosed in the referenced patents. As seen best in **FIG. 3A,** the sensor device 30 typically includes a carrier or substrate 36 on which an integrated circuit (IC) 38 and other components, such as a capacitor 40, are mounted in hybrid fashion.

[0027] Whereas the carrier or substrate 36 shown in **FIG. 3A** serves as a foundation or base on which hybrid electronic circuitry is formed, the present invention re-

lates to an embodiment where the carrier or substrate 36 actually comprises the substrate in which the IC 38 is formed.

[0028] For the embodiment shown in **FIGS. 3A-3D,** all of the components of the hybrid circuit are hermetically sealed within a cavity formed by a lid or cover 42 which is bonded to the substrate 36. As will be evident from the description that follows, a significant advantage of the present invention is that this lid or cover 42 is not required in the embodiment of the invention disclosed herein.

[0029] Returning to **FIGS. 3A-3D,** proximal pads or terminals 13 and 15, as well as distal pads or terminals 17 and 19, remain outside of the hermetically sealed part of the hybrid circuit created by the cover 42. These proximal and distal pads, however, are electrically connected to the circuitry within the hermetically sealed part through suitable feedthrough connections. One preferred manner of making such feedthrough connection is to use a feedthrough connection that passes through the carrier or substrate in the stair-step manner (including both vertical and horizontal segments) is disclosed in U.S. Patent No. 5,750,926.

[0030] Still with reference to **FIGS. 3A-3D,** on the side of the carrier or substrate opposite the hybrid electrical circuitry, a suitable electrochemical sensor 44, or other desired type of sensor or stimulator, may be formed or located. A type of electrochemical sensor that may be used, for example, is the enzyme electrode sensor described in U.S. Patent No. 5,497,772 and in particular, in **FIGS. 2A, 2B, 2C, 3, 4A** and **4B** of that patent. However, it is to be emphasized that the precise nature of the sensor 44, or other implantable element used within the sensor device 30, is not critical to the present invention. All that matters is that the sensor or other element be implantable, and that it provide a desired function, e.g., sense a certain type of parameter or substance, or generate a certain type of signal, in response to an appropriate control signal or signals.

[0031] Whatever type of control signal(s) or output signal(s) is/are generated by the sensor 44, or other element, such signal(s) may be communicated from the hybrid circuit side of the carrier or substrate 36 (which is the top side as the sensor device 30 is oriented in **FIG. 3B** or **FIG. 3D,** and which top side includes the hermetically sealed portion of the device) to the sensor side of the sensor device 30 (which is the bottom side as shown in **FIG. 3B** or **FIG. 3D**) by way of appropriate hermetically-sealed feedthroughs that pass step-wise from the hybrid (top) side of the sensor device 30 through the substrate or carrier, e.g., in the manner set forth in the above-referenced '926 patent, to the sensor (bottom) side of the sensor device 30.

[0032] For example, where the sensor comprises a glucose sensor of the type taught in U.S. Patent No. 5,497,772, there may be five conductors that electrically interface with the main elements (electrodes) of the sensor, as seen best in **FIG. 4A** of the '772 patent. Where such a glucose sensor is employed, these five conductors thus interface with the hybrid electrical circuitry found on the top side of the carrier 36 using appropriate feedthroughs that hermetically pass step-wise through the carrier 36, i.e., that pass through the carrier using both vertical horizontal segments, as taught in the '926 patent.

[0033] As mentioned above, the application is directed to a device 30 that does not employ a carrier 36, per se, as shown in **FIGS. 3A, 3B, 3C, 3D** and **FIG.** 4, wherein the control electronics are positioned on one side (the top side) of the carrier 36, and the sensor, or other device being used with or controlled by the electronics, is placed on the other side (the bottom side) of the carrier. Rather, the ceramic or substrate on which the IC 38 is formed itself functions as the carrier. In the parent application, this is accomplished using vias that are formed in a substrate, or between various layers of an integrated circuit as the integrated circuit (IC) is formed, function as hermetic feedthroughs, with selected layers and traces being coated as needed with aluminum oxide, or other oxide coatings, in the manner taught in the aforementioned '926 patent, and/or in U.S. Patent No. 6,043,437 in order to seal appropriate sections or portions of the IC so that the coated IC may itself be implanted. Advantageously, when this is done, the sensor 44 or other implantable element used with or controlled by the IC may be formed on the back side (non-active side) of the IC substrate. Thus, a carrier, per se, is not needed because the IC substrate functions as the carrier, and a lid or cover 42 is not needed.

[0034] An important advantage achieved with embodiments of the application is that the electrical circuitry formed within the substrate of the sensor allows the implantable device to be daisy chained with other similar implantable devices, while still allowing each individual device to be individually addressed, controlled and monitored from a single controller 20. Such electrical circuitry, frequently referred to hereafter as the interface/control circuitry, is shown in **FIGS. 3A, 3B, 3C, 3D** and **4** as being located on the "top" side of the carrier 36, predominantly underneath the cover 42 in a hermetically sealed portion of the sensor device 30. However, it is to be understood that in accordance with the application, such interface/control is actually formed within the substrate, on an active side of such substrate, and coated, as required, with a suitable coating, so as to be hermetically sealed.

[0035] The configuration of **FIG. 2** is especially well-suited where several of the implantable devices are to be daisy-chained together to form a single lead 32, as shown in **FIG. 4.** As seen in **FIG. 4,** three sensor-type devices 30a, 30b, and 30c of the type shown in **FIGS. 3A-3D** are connected together via lead segments 46a, 46b, and 46c. Each of the lead segments 46a, 46b, and 46c, contain two conductors 14, 16, and may be constructed in any suitable manner, e.g., with the two conductors being spirally wound within the lead segments, and with the spiral windings being encased or covered

within a sheath of silicone rubber, as in known in the lead art. (Note, that for purposes of **FIG. 4** each of the two conductors 14, 16 within the lead 32 is considered as one conductor, even though each is segmented within the individual lead segments 46a, 46b and 46c as it connects from the distal pad of one device to the proximal pad of another device.) A distal cap 34 covers the distal pads of the end, or most-distal, sensor device 30c of the lead 32.

[0036] Turning next to **FIGS. 5A** and **5B,** a substrate sensor 50 not made in accordance with the present invention is shown. Top and sectional side views of such substrate sensor 50 are shown in **FIGS. 5A** and **5B,** respectively. Advantageously, the substrate sensor 50 does not use hybrid electronic circuitry nor require a hermetically-sealed lid or cover. Rather, the substrate sensor 50 includes a substrate 52, e.g., a silicone or ceramic substrate of the type commonly used in the formation of CMOS or other integrated circuits.

[0037] Electronic circuitry is formed as an integrated circuit 70 on an active side of the substrate 52, within a region 54, in conventional manner, e.g., in accordance with conventional CMOS processing techniques, and may extend down below the surface into the substrate 52. Hence, the circuit region 54 is shown in **FIG. 5B** as extending slightly into the body of the substrate 52. On the active surface of the substrate sensor 50, as seen in **FIG. 5A,** connection pads 13, 15, 17 an 19 may be formed to allow the sensor substrate to be daisy-chained with other sensors, as taught in the previously referenced U.S. Patent No. 5,999,848.

[0038] The integrated circuit 70 (shown in the example of **FIG. 5B** as extending to the edge of the substrate 52) includes a plurality of electrically conductive pads 72 formed on its upper surface for communicating and/or providing power to the integrated circuit 70. Such pads are formed from an electrically conductive material, e.g., aluminum, or the like, in a conventional matter. The majority of the substrate 52 and the integrated circuit 70 formed within are coated with a biocompatible insulating material, e g., alumina, zirconia, or an alloy or alumina and zirconia, to hermetically encapsulate the package forming the substrate sensor 50 using an encapsulation layer 56. Significantly, the present invention provides electrical connection through the encapsulation layer 56 to the electrically conductive pads 72 while maintaining the hermeticity of the package forming the substrate sensor 50. In a first embodiment, shown in **FIG. 5B,** a metallic via (e.g., forming pads 15 and 19), preferably formed from platinum, passes through the encapsulation layer 56 in order to provide external electrical connection to the electrically conductive pads 72. The vias are preferably made hermetic in one of two techniques. In a first technique, the layer of platinum forming the via is made thick enough, e.g., at least 5 microns, to overcome any non-uniformity of the platinum that would tend to allow leakage. In a next technique, described further below, ion beam deposition can be used to form the platinum vias. Since this process will form a more uniform layer of platinum, the thickness of the platinum vias may be somewhat decreased while still being hermetic.

[0039] Turning next to **FIGS. 6A and 6B,** an alternative technique which is in accordance with the invention is shown for providing external hermetic electrical connections through the encapsulation layer 56 to the electrically conductive pads, e.g., 72a and 72b, on the integrated circuit 70 (shown in the example of **FIG. 6B** as extending to the edge of the substrate 52). In this technique, a metallic (e.g., aluminum, platinum) trace, e.g., trace 74, is formed essentially parallel to the surface of the substrate 52 and the integrated circuit 70. A first end of the trace 74 is electrically coupled to the electrically conductive pad, e.g., pad 72b. A second end 58 of the trace 74 is exposed through the encapsulation material 56 to form a pad 19 accessible at its outer surface. In the technique shown in **FIG. 6B,** hermeticity is achieved via the serpentine routing of the electrical connection from the second end 58 of trace 74 to the conductive pad 72b and by the relative length of the metal trace 74, e.g., the length of the metal trace is preferably at least 100 microns. Preferably, the metal trace is surrounded by thin, e.g., 1 micron, layers of encapsulation material, typically deposited as one or more fabrication steps.

[0040] Additional electrical connections, e.g., for forming sensing electrodes E1 and E2 (see **FIG. 6A**) may also be formed on the same surface as the power/communication pads 13, 15, 17, 19 and hermetically connected to the integrated circuit 70 in a similar manner. Such sensing electrodes may be used in combination with the integrated circuit 70 to form a sensor as described in the aforementioned patents. Advantageously, when desired, the previously described technique allows all of the connections, circuitry and sensing electrodes to be formed on the same surface of the substrate 52 and thus facilitates the fabrication of multiple, e.g., pairs of, sensors as described further below in the description of **FIGS. 9 and 10.**

[0041] **FIG.** 7 shows a partial cross section of a next alternative embodiment of a technique for providing a hermetic electrical connection to the semiconductor formed on the substrate. This embodiment is similar to that shown in reference to **FIG. 6A** except that additional layers of interconnected metallic electrically conductive traces, 74', 74" surrounded by additional encapsulation layers 56', 56", 56"' are used to further enhanced the hermeticity of the electrical connection (at some cost in increased thickness of the package).

[0042] Various techniques may be used to apply a coating of encapsulation layer 56, e.g., alumina insulation, over the substrate 52. A preferred technique, for example, is to use an ion beam deposition (IBD) technique. IBD techniques are known in the art, as taught, e.g. in U.S. Patent Nos. 4,474,827 or 5,508,368.

[0043] Using such IBD techniques, or similar techniques, the desired alumina or other layer 56 may be deposited on all sides of the substrate 52 as illustrated

in **FIG. 8.** As seen in **FIG. 8,** the substrate 52 is placed on a suitable working surface 401 that is rotatable at a controlled speed. The working surface 401 with the substrate 52 thereon (once the circuitry and electrodes have been formed thereon) is rotated while a beam 421 of ions exposes the rotating surface. Assuming the substrate 52 has six sides, five of the six sides are exposed to the beam 421 as it rotates, thereby facilitating application of the desired layer of alumina onto the five exposed sides of the object. After sufficient exposure, the object is turned over, thereby exposing the previously unexposed side of the substrate to the beam, and the process is repeated. In this manner, four of the sides of the substrate 52 may be double exposed but such double exposure simply results in a thicker encapsulation layer 56 of alumina on the double-exposed sides.

[0044] Other techniques, as are known in the art, may also be used to apply the alumina encapsulation layer 56 to the object.

[0045] The steps typically followed in applying an encapsulation layer 56 of alumina to the substrate 52 include:

(a) Sputtering a layer of titanium of about 300 Å thick over any metal conductor or other object that is to be coated with the alumina.

(b) If selective application of the alumina to the object is to be made, spinning a photosensitive polyamide onto the substrate.

(c) Applying a mask that exposes those areas where alumina is not to be applied.

(d) Shining ultraviolet (UV) light through the mask to polymerize the polyamide. Where the UV light illuminates the polyamide is where aluminum oxide will not be deposited. Thus, the polymerizations of the polyamide is, in effect, a negatively acting resist.

(e) Developing the photoresist by washing off the unpolymerized polyamide with xylene, or an equivalent substance. Once the unpolymerized polyamide has been washed off, the ceramic (or other component) is ready for aluminum oxide deposition.

(f) If selective application of the alumina is not to be made, i.e., if alumina is to be applied everywhere, or after washing off the unpolymerized polyamide, depositing aluminum oxide to a prescribed thickness, e.g., between 4 and 10 microns, e.g., 6 microns, over the subject using ion enhanced evaporation (or sputtering), IBD, or other suitable application techniques.

(g) During application of the coating, rotate and/or reposition the substrate as required in order to coat all sides of the substrate, e.g., as shown in **FIG. 8,** with a coating of sufficient thickness. This step may require several iterations, e.g., incrementally depositing a thin layer of alumina, checking the layer for the desired thickness or properties, and repeating the repositioning, depositing, and checking steps as required until a desired thickness is achieved, or until the coating exhibits desired insulative and/or hermeticity properties.

(h) Breaking or scribing the aluminum oxide that resides over the polyamide, if present, with a diamond scribe, or laser, controller by a computerized milling machine. This permits a pyrana solution, explained below, to get under the oxide for subsequent lift off of the aluminum oxide.

(i) Lifting off the polyamide and unwanted aluminum oxide after soaking the substrate in pyrana solution (H_2SO_4 x H_2O_2 x 2 heated to 60° C). Soaking should occur for 30 to 60 minutes, depending on the thickness of the polyamide layer.

[0046] The above described coating method is substantially the same as that disclosed in U.S. Patent No. 6,043,437. It should be apparent to one of ordinary skill in the art that the aforementioned IBD techniques may be adapted to selectively deposit a layer of platinum or the like of a biocompatible electrically conductive metal to form the via and electrodes used to provide an external electrical interconnection to the semiconductor formed within. Advantageously, by using such an IBD technique, the platinum or the like metallic layer can be made sufficiently uniform to provide a hermetic connection.

[0047] **FIG. 9** illustrates a sensor assembly 100 formed by placing two sensor substrates 50 back-to-back so that the electrodes of both sensor substrates face outward. The protective encapsulation layer 56 is not shown in **FIG. 9,** but it is presumed to be present.

[0048] **FIG. 10** depicts the use of the sensor assembly 100 of **FIG. 9** within a sheath 102 and membrane 104 so as to form an electrochemical sensor assembly 110. The sheath 102 surrounds the sensor assembly 100 and forms a reservoir therein into which a suitable solution 108, e.g., a saline solution, is held. The membrane 104 surrounds the sheath 102. Pockets 106 are formed in the membrane 104 over a selected working electrode. A suitable enzyme 107 is placed inside of the pockets. Windows 109 expose the enzyme 107 to the surrounding environment held in the pockets 106.

[0049] Operation of the electrochemical sensor assembly 110 may be substantially as described in the '163 patent and the other previously referenced patents. However, in the aforedescribed structure of sensor assembly 110, the sensing windows 109 are located on both sides of the assembly, thereby providing a broader exposure coverage or "view" for the operation of the sensor.

[0050] As described above, it is thus seen that the present invention provides and implantable sensor having electrodes and electronic circuitry, where the electronic circuitry and electrodes are formed on or in the same substrate material, e.g., a semiconductor substrate of the same type used in the formation of complementary metal oxide semiconductor (CMOS) integrated circuits.

[0051] It is a further seen that the invention provides and implantable sensor, including electrodes and electronic circuitry, that does not require a lid or cover for hermetically sealing hybrid electronic circuitry on one

side of a substrate; thereby allowing the sensor to be significantly thinner than would otherwise be possible.

[0052] While the invention herein disclosed has been described by means of specific embodiments and applications thereof, numerous modifications and variations could be made thereto by those skilled in the art without departing from the scope of the invention set forth in the claims. For example, it is generally desirable that the corners of the assembly be rounded (see corner 62 in **FIG. 6B**) to further ensure hermeticity. Sandblasting and acid etching techniques can accomplish this rounding. Furthermore, while pads, e.g., 19, are generally positioned within a shallow cavity in the encapsulation layer 56, it may be desired to bond conductive beads or pads to assist external connection or to stagger/layer the surrounding encapsulation layer to minimize any stress on external connections to the pads, e.g., 19. Such variations are considered to be within the scope of the present invention. It is therefore to be understood that within the scope of the claims, the invention may be practiced otherwise than as specifically described herein.

Claims

1. A hermetically sealed package (50; 100; 102) suitable for implantation in living tissue, said package comprising:

a semiconductor substrate (52) having a plurality of surfaces and having an integrated circuit (70) formed as an integral portion of at least one of said surfaces, said integrated circuit having one or more electrically conductive pads (72; 72a, 72b) for communicating and/or providing power to said integrated circuit;

one or more electrical pathways (74; 74', 74") for providing hermetic electrical connection to said one or more electrically conductive pads, said pathways having first ends coupled to said one or more pads (72; 72a, 72b) and second ends (13, 15, 17, 19) exposed for external electrical connection from said sealed package; and an insulating coating material (56; 56', 56") coating and encapsulating said integrated circuit and said semiconductor substrate surfaces except for selected portions of said second ends (13, 15, 17, 19) of said electrical pathways wherein said hermetically sealed package is thereby suitable for implantation in living tissue;

wherein each of said electrical pathways comprises:

a first electrically conductive via electrically coupled to one of said pads (72a, 72b);

a metal trace (74) oriented essentially parallel to the surface of the semiconductor substrate (52) on which the integrated circuit (70) is formed and electrically coupled at said first end by said first via to said one or more pads and exposed at, said second end (15, 19) of the pathway; and

wherein

said electrical pathway is surrounded by the insulating coating material (56).

2. The hermetically sealed package of claim 1, wherein said pathways are formed from electrically conductive material having a thickness sufficient to inhibit leakage due to any non-uniformity of the conductive material.

3. The hermetically sealed package of claim 1 or 2, wherein said electrical pathways are comprised of platinum, and wherein said electrical pathways comprise a biocompatible hermetic via.

4. The hermetically sealed package of claim 3 wherein said electrical pathways are made hermetic by having a thickness of at least 5 microns.

5. The hermetically sealed package of claim 1, wherein said biocompatible insulation material (56) is selected from the group of alumina, zirconia or an alloy of alumina and zirconia.

6. The hermetically sealed package of claim 1 wherein said second end (15, 19) of said metal trace is biocompatible.

7. The hermetically sealed package of claim 6 wherein said second end (15, 19) of said metal trace is platinum.

8. The hermetically sealed package of claim 1 wherein at least one of said electrically conductive pathways is comprised of:

a plurality of metal traces (74', 74") having first and second ends, including at least an innermost trace (74') closest to said semiconductor substrate (52) and an outermost trace (74") furthest from said semiconductor substrate, each adjacent pair of metal traces separated by an insulating material (56') sandwiched in-between so as to form a hermetic seal between said metal traces;

at least one interconnection via surrounded by said insulating material (56') for interconnecting said adjacent pairs of metal traces;

at least one innermost via for interconnecting said innermost trace (74') to at least one of said pads (72) on said integrated circuit (70) at the first ends of the pathways;

an insulating material for encapsulating said plurality of metal traces, said integrated circuit and

said semiconductor substrate, wherein the second end (19) of at least one outermost metal trace (74") is at least partially exposed through the encapsulating insulating material (56) at the second end of the pathways for external communication; and wherein
said combination of metal traces, sandwiched insulating material, encapsulating material and vias provides a hermetic communication path to said integrated circuit from a location external to said implantable package.

9. The hermetically sealed package of claim 1 wherein said integrated circuit (70) is formed on a first surface of the semiconductor substrate (52) and said electrical pathways (74; 74' 74") from said integrated circuit extend outward from said first surface.

10. The hermetically sealed package of claim 9 wherein said semiconductor substrate has a second surface on a side opposite of said first surface of said substrate and said second surface of said substrate is formed without electrical pathways or an integrated circuit.

11. A method of forming an electrically conductive hermetic connection to a hermetically sealed integrated circuit, said method comprising the steps of:

forming an integrated circuit (70) on a surface of a semiconductor substrate (52), said integrated circuit (70) having one or more electrically conductive pads (72; 72a, 72b) for communicating and/or providing power to said integrated circuit;
forming one or more electrical pathways (74; 74', 74") for providing hermetic electrical connection to said one or more electrically conductive pads (72; 72a, 72b), said pathways having first ends coupled to said one or more pads and second ends (13, 15, 17, 19) exposed for external electrical connection from said sealed integrated circuit (70); and
coating and encapsulating said semiconductor substrate and said integrated circuit except for selected portions of said second ends of said electrical pathways with an insulating coating material (56; 56', 56") wherein said hermetically sealed circuit is thereby suitable for implantation in living tissue;

wherein the step of forming one or more electrical pathways comprises at least in part the steps of:

forming a first electrically conductive via electrically coupled to one of said pads (72a, 72b);
forming a metal trace (74) oriented essentially parallel to the surface of the semiconductor substrate (52) on which the integrated circuit (70) is formed and electrically coupled at said first end by said first via (72a, 72b) to said one ore more pads an exposed at said second end (15, 19) of said pathway; and
surrounding said electrical pathway by a the insulating coating material (56).

12. The method of claim 11, where said pathways are formed from electrically conductive material having a thickness sufficient to inhibit leakage due to any non-uniformity of the conductive material.

13. The method of claim 11 or 12 wherein the step of forming one or more electrical pathways comprises the step of forming said electrical pathways (74; 74', 74") from platinum such that said electrical pathways are biocompatible.

14. The method of claim 13 wherein the step of forming said electrical pathways from platinum comprises depositing said platinum using ion beam deposition to ensure sufficient uniformity.

15. The method of claim 13 wherein the step of forming said electrical pathways from platinum comprises depositing a layer of platinum of at least 5 microns to cause said platinum electrical pathways (74; 74', 74") to be hermetic.

16. The method of claim 11 wherein the step of surrounding said electrical pathway comprises depositing alumina to surround said electrical pathway (74).

17. The method of claim 11 wherein the step of forming a second electrically coupled via comprises forming said second via from a biocompatible material.

18. The method of claim 11 wherein the step of forming a second electrically coupled via comprises forming said second via from platinum such that said second via is biocompatible.

19. The method of claim 11 wherein the step of forming one or more electrical pathways comprises at least in part the steps of:

forming a plurality of metal traces (74', 74") having first and second ends, including at least an innermost trace (74') closest to said semiconductor substrate (52) and an outermost trace (74") furthest from said semiconductor substrate, each adjacent pair of metal traces (74', 74") separated by an insulating material (56') sandwiched in-between so as to form a hermetic seal between said metal traces;
forming at least one interconnection via surrounded by said insulating material (56') for in-

terconnecting said adjacent pairs of metal traces;
forming at least one innermost via for interconnecting said innermost trace (74') to at least one of said pads on said integrated circuit at the first ends of the pathways;
depositing an insulating material (56) for encapsulating said plurality of metal traces (74', 74"), said integrated circuit (70) and said semiconductor substrate (52);
enabling at least a portion of one said second end (19) of an outermost metal trace (74") to be partially externally exposed through the encapsulating insulating material (56) at the second ends of the pathways for external communication; and wherein
said combination of metal traces, sandwiched insulating material, encapsulating material and vias provides a hermetic communication path to said integrated circuit from a location external to said implantable package.

20. The method of claim 19 additionally comprising the step of rounding at least one corner of said encapsulated integrated circuit.

21. The method of claim 20 wherein said rounding step comprises sandblasting.

22. The method of claim 20 wherein said rounding step comprises acid etching.

23. A hermetically sealed package according to any one of claims 1 to 10, without a lid or cover for the encapsulated substrate.

24. A method according to any one of claim 11 to 22, without providing a lid or cover for the encapsulated substrate.

25. A method according to any one of claims 11 to 22, wherein the step of encapsulating said semiconductor substrate and said integrated circuit comprised performing ion beam deposition of the insulating coating material.

Patentansprüche

1. Hermetisch dicht abgeschlossene Baugruppe (50; 100; 102), die zur Implantation in Lebendgewebe geeignet ist, mit:

einem Halbleiter-Substrat (52) mit einer Vielzahl von Oberflächen und einer integrierten Schaltung (70), die als integraler Bestandteil mindestens einer der Oberflächen ausgebildet ist und eine oder mehr elektrisch leitfähige Anschlussflächen (Pads) (72; 72a, 72b) für die Signalübertragung und/oder die Stromzufuhr zur integrierten Schaltung aufweist;
einem oder mehr elektrischen Leitungspfaden (74; 74'; 74") zum Herstellen einer hermetisch dichten elektrischen Verbindung zu einer oder mehr der elektrisch leitfähigen Anschlussflächen, wobei die Leitungspfade an ersten Enden mit der einen oder mehr Anschlussflächen (72; 72a, 72b) verbunden sind und an zweiten Enden (13, 15, 17, 19) freiliegen, zur externen elektrischen Verbindung zur abgeschlossenen Baugruppe; und
einem isolierenden Beschichtungsmaterial (56; 56', 56"), das mit Ausnahme ausgewählter Teile der zweiten Enden (13, 15, 17, 19) der elektrischen Leitungspfade die integrierte Schaltung und das Halbleitersubstrat abdeckt und einkapselt, so dass die hermetisch dicht abgeschlossene Baugruppe für die Implantation in Lebendgewebe geeignet ist;

wobei die elektrischen Leitungspfade jeweils aufweisen:

einen ersten elektrisch leitfähigen Durchsteiger, der mit einer der Anschlussflächen (72a, 72b) elektrisch verbunden ist;
eine Metall-Leiterbahn (74), die zu der Oberfläche des Halbleiter-Substrats (52), auf der die integrierte Schaltung (70) ausgebildet ist, im Wesentlichen parallel ausgerichtet ist, und an dem ersten Ende durch den ersten Durchsteiger mit der einen oder mehr Anschlussflächen verbunden ist und am zweiten Ende (15, 19) der Leiterbahn freiliegt;
und wobei der elektrische Leitungspfad von dem isolierenden Beschichtungsmaterial (56) umgeben ist.

2. Hermetisch dichte Baugruppe nach Anspruch 1, deren Leitungspfade aus einem elektrisch leitfähigen Werkstoff dick genug ausgebildet sind, um Leckströme in Folge von Ungleichmäßigkeiten des leitfähigen Werkstoff zu unterdrücken.

3. Hermetisch dichte Baugruppe nach Anspruch 1 oder 2, deren elektrischen Leitungspfade aus Platin bestehen und einen biokompatiblen, hermetisch dichten Durchsteiger aufweisen.

4. Hermetisch dichte Baugruppe nach Anspruch 3, deren Leitungspfade **dadurch** hermetisch dicht werden, dass sie mindestens 5 Mikron dick sind.

5. Hermetisch dichte Baugruppe nach Anspruch 1, bei der das biokompatible Isolationsmaterial (56) aus der aus Aluminiumoxid, Zirconoxid und einer Alumi-

niumoxid-Zirconoxid-Legierung bestehenden Gruppe gewählt ist.

6. Hermetisch dichte Baugruppe nach Anspruch 1, bei der das zweite Ende (15, 19) der Metall-Leiterbahn biokompatibel ist.

7. Hermetisch dichte Baugruppe nach Anspruch 6, bei der das zweite Ende (15, 19) der Metall-Leiterbahn aus Platin besteht.

8. Hermetisch dichte Baugruppe nach Anspruch 1, bei der mindestens einer der elektrisch leitfähigen Leitungspfade aufweist:

eine Vielzahl von Metall-Leiterbahnen (74', 74") mit ersten und zweiten Enden, von denen mindestens eine am weitesten innen liegende Leiterbahn (74') dem Halbleiter-Substrat (52) am nächsten und eine am weitesten außen liegende Leiterbahn vom Halbleiter-Substrat am weitesten entfernt liegt, wobei jeweils zwei nebeneinander liegende Metall-Leiterbahnen von einem isolierenden Material (56') getrennt sind, das dicht zwischen ihnen so eingeschichtet ist, dass zwischen den Metall-Leiterbahnen ein hermetisch dichter Abschluss entsteht;
mindestens einen Verbindungs-Durchsteiger, der vom isolierenden Material (56') umgeben ist und die nebeneinander liegenden zwei Metall-Leiterbahnen verbindet;
mindestens einen am weitesten innen liegenden Durchsteiger zum Verbinden der innersten Leiterbahn (74') mit mindestens einer der Anschlussflächen (72) der integrierten Schaltung (70) an den ersten Enden der Leitungspfade; und
ein isolierendes Material zum Einkapseln der Vielzahl von Metall-Leiterbahnen, der integrierten Schaltung und des Halbleiter-Substrats, wobei zur externen Signalübertragung das zweite Ende (19) mindestens einer am weitesten außen liegenden Metall-Leiterbahn (74") durch das Einkapselungsmaterial (56) am zweiten Ende der Leitungspfade hindurch mindestens teilweise freiliegt;
wobei die Kombination aus Metall-Leiterbahnen, eingeschichtetem isolierendem Material, Einkapselungsmaterial und Durchsteigern einen hermetisch dichten Übertragungsweg von einem Ort außerhalb der hermetisch dicht abgeschlossenen Baugruppe zur integrierten Schaltung herstellt.

9. Hermetisch dichte Baugruppe nach Anspruch 1, bei der die integrierte Schaltung (70) auf einer ersten Oberfläche des Halbleiter-Substrats (52) ausgebildet ist und die elektrischen Leitungspfade (74; 74', 74") von der integrierten Schaltung weg und von der ersten Oberfläche auswärts verlaufen.

10. Hermetisch dichte Baugruppe nach Anspruch 9, bei der auf seiner der ersten gegenüberliegenden Seite das Halbleiter-Substrat eine zweite Oberfläche aufweist, die ohne elektrische Leitungsbahnen oder eine integrierte Schaltung gebildet ist.

11. Verfahren zum Herstellen einer elektrisch leitfähigen, hermetisch abgeschlossenen Verbindung zu einer dicht eingeschlossenen integrierten Schaltung, mit folgenden Schritten:

Ausbilden einer integrierten Schaltung (70) auf einer Oberfläche eines Halbleiter-Substrats (52), wobei die integrierte Schaltung (70) einen oder mehr elektrisch leitfähige Anschlussflächen (72; 72a, 72b) zur Signalübertragung zu/von der integrierten Schaltung und/oder für die Stromzufuhr aufweist;
Ausbilden einer oder mehr elektrischer Leitungspfade (74; 74', 74") zum Herstellen hermetisch dichter elektrischer Verbindungen zu der einen oder mehr elektrisch leitfähigen Anschlussflächen (72; 72a, 72b), wobei die Leitungspfade an ersten Enden mit der einen oder mehr Anschlussflächen verbunden sind und an zweiten Enden (13, 15, 17, 19) freiliegen, um von der dichten integrierten Schaltung (70) abgehende elektrische Außenverbindungen herzustellen; und
Beschichten und Einkapseln des Halbleiter-Substrats und der integrierten Schaltung - mit Ausnahme ausgewählter Teile der zweiten Enden - mit einem isolierenden Beschichtungsmaterial (56; 56', 56"), so dass die dichte abgeschlossene integrierte Schaltung für das Implantieren in Lebendgewebe geeignet ist;

wobei das Ausbilden eines oder mehrerer elektrischer Leitungsbahnen mindestens teilweise die folgenden Schritte aufweist:

Ausbilden eines elektrisch leitfähigen ersten Durchsteigers, der mit einer der Anschlussflächen (72a, 72b) verbunden ist;
Ausbilden einer Metall-Leiterbahn (74), die im Wesentlichen parallel zu der Oberfläche des Halbleiter-Substrats (52) gerichtet ist, auf der die integrierte Schaltung (70) ausgebildet ist, und die am ersten Ende mittels des ersten Durchsteigers (72a, 72b) elektrisch mit der einen oder mehrAnschlussflächen verbunden ist und an den zweiten Enden (15, 19) des Leitungspfads freiliegen; und
Umgeben des elektrischen Leitungspfads mit dem isolierenden Beschichtungsmaterial (56).

12. Verfahren nach Anspruch 11, bei dem die Leitungspfade aus einem elektrisch leitfähigen Werkstoff in einer Dicke ausgebildet werden, die genügt, um Leckströme in Folge von Ungleichmäßigkeiten des leitfähigen Materials zu unterdrücken.

13. Verfahren nach Anspruch 11 oder 12, bei dem das Ausbilden eines oder mehr elektrischer Leitungspfade den Schritt des Ausbildens des elektrischen Leitungspfade (74; 74', 74") aus Platin aufweist derart, dass die elektrischen Leitungspfade biokompatibel sind.

14. Verfahren nach Anspruch 13, bei dem das Ausbilden der elektrischen Leitungspfade aus Platin das Auftragen des Platins durch Ionenstrahlbeschichtung beinhaltet, um eine ausreichende Gleichmäßigkeit zu gewährleisten.

15. Verfahren nach Anspruch 13, bei dem das Ausbilden der elektrischen Leitungspfade aus Platin das Auftragen einer Platinschicht in einer Dicke von mindestens 5 Mikron beinhaltet, damit die elektrischen Platin-Leitungspfade (74; 74', 74") hermetisch dicht sind.

16. Verfahren nach Anspruch 11, bei dem das Umgeben des elektrischen Leitungspfads das Auftragen von den elektrischen Leitungspfad (74) umgebenden Aluminiumoxid beinhaltet.

17. Verfahren nach Anspruch 11, bei dem das Ausbilden eines elektrisch verbundenen zweiten Durchsteigers das Ausbilden desselben aus einem biokompatiblen Werkstoff beinhaltet.

18. Verfahren nach Anspruch 11, bei dem das Ausbilden eines elektrisch verbundenen zweiten Durchsteigers das Ausbilden desselben aus Platin beinhaltet derart, dass der zweite Durchsteiger biokompatibel ist.

19. Verfahren nach Anspruch 11, bei dem das Ausbilden eines oder mehrerer elektrischer Leitungspfade mindestens teilweise die folgenden Schritte aufweist:

Ausbilden einer Vielzahl von Metall-Leiterbahnen (74', 74") mit ersten und zweiten Enden, wobei mindestens eine am weitesten innen liegende Leiterbahn (74') dem Halbleitersubstrat (52) am nächsten und eine am weitesten außen liegende Leiterbahn (74") vom Halbleiter-Substrat am weitesten entfernt liegt und jeweils zwei nebeneinander liegende Metall-Leiterbahnen (74', 74") von einem isolierenden Material (56') getrennt sind, das zwischen sie eingeschichntet ist derart, dass zwischen den Metall-Leiterbahnen ein hermetisch dichter Abschluss entsteht;

Ausbilden mindestens eines vom isolierenden Material (56') umgebenen Durchsteigers zum Verbinden der nebeneinanderliegenden zwei Metall-Leiterbahnen;

Ausbilden mindestens eines am weitesten innen liegenden Durchsteigers zum Verbinden der innersten Leiterbahn (74') mit mindestens einer der Anschlussflächen der integrierten Schaltung an den ersten Enden der Leitungspfade;

Auftragen eines isolierenden Materials (56) zum Einkapseln der Metall-Leiterbahnen (74', 74"), der integrierten Schaltung (70) und des Halbleiter-Substrats (52); und

mindestens teilweises Freilassen mindestens eines Teils eines zweiten Endes (19) einer am weitesten außen liegenden Metall-Leiterbahn (74") nach außen durch das Einkapselungsmaterial (56) hindurch an den zweiten Enden der Leitungspfade für das Herstellen externer Verbindungen von/zu ihnen;

wobei die Kombination aus Metall-Leiterbahnen, eingeschichtetem Isolier- und Einkapselungsmaterial sowie den Durchsteigern einen hermetisch dichten Übertragungsweg von einem Ort außerhalb der implantierbaren Baugruppe zur integrierten Schaltung hin herstellt.

20. Verfahren nach Anspruch 19 mit dem zusätzlichen Schritt eines Abrundens mindestens einer Ecke der eingekapselten integrierten Schaltung.

21. Verfahren nach Anspruch 20, bei dem das Abrunden durch Sandstrahlen erfolgt.

22. Verfahren nach Anspruch 20, bei dem das Abrunden durch Säureätzen erfolgt.

23. Hermetisch dichte Baugruppe nach einem der Ansprüche 1 bis 10 ohne Deckel oder Abdeckung für das gekapselte Substrat.

24. Verfahren nach einem der Ansprüche 11 bis 22 ohne Bereitstellung eines Deckels oder einer Abdeckung für das gekapselte Substrat.

25. Verfahren nach einem der Ansprüche 11 bis 22, bei dem zum Einkapseln des Halbleiter-Substrats und der integrierten Schaltung das isolierende Beschichtungsmaterial durch Ionenstrahlbeschichtung aufgetragen wird.

Revendications

1. Conditionnement hermétiquement scellé (50 ; 100 ; 102) adapté pour une implantation dans un tissu vivant, ledit conditionnement comprenant :

un substrat semi-conducteur (52) ayant une pluralité de surfaces et ayant un circuit intégré (70) formé comme une partie monobloc d'au moins une desdites surfaces, ledit circuit intégré ayant un ou plusieurs disques électriquement conducteurs (72 ; 72a, 72b) pour communiquer et/ou fournir de l'énergie audit circuit intégré ;
un ou plusieurs chemins électriques (74 ; 74', 74") pour fournir audit ou auxdits disques électriquement conducteurs une connexion électrique hermétique, lesdits chemins ayant des premières extrémités couplées audit ou auxdits disques (72 ; 72a, 72b) et des secondes extrémités (13, 15, 17, 19) exposées pour une connexion électrique externe à partir dudit conditionnement scellé ; et
un matériau de revêtement isolant (56 ; 56', 56") revêtant et encapsulant ledit circuit intégré et lesdites surfaces de substrat semi-conducteur sauf pour des parties sélectionnées desdites secondes extrémités (13, 15, 17, 19) desdits chemins électriques, ledit conditionnement hermétiquement scellé étant ainsi adapté pour une implantation dans un tissu vivant ;

dans lequel chacun desdits chemins électriques comprend :

une première traversée électriquement conductrice, électriquement couplée à l'un desdits disques (72a 72b) ;
une trace métallique (74) orientée sensiblement parallèlement à la surface du substrat semi-conducteur (52) sur laquelle le circuit intégré (70) est formé et électriquement couplée au niveau de ladite première extrémité par ladite première traversée audit ou auxdits disques et exposée au niveau de ladite seconde extrémité (15, 19) du chemin ; et dans lequel
ledit chemin électrique est entouré du matériau de revêtement isolant (56).

2. Conditionnement hermétiquement scellé selon la revendication 1, dans lequel lesdits chemins sont formés à partir d'un matériau électriquement conducteur ayant une épaisseur suffisante pour empêcher une fuite due à une quelconque non-uniformité du matériau conducteur.

3. Conditionnement hermétiquement scellé selon la revendication 1 ou 2, dans lequel lesdits chemins électriques sont constitués de platine, et dans lequel lesdits chemins électriques comprennent une traversée hermétique biocompatible.

4. Conditionnement hermétiquement scellé selon la revendication 3, dans lequel lesdits chemins électriques sont rendus hermétiques en ayant une épaisseur d'au moins 5 microns.

5. Conditionnement hermétiquement scellé selon la revendication 1, dans lequel ledit matériau d'isolation biocompatible (56) est choisi parmi le groupe comprenant l'alumine, le zircone ou un alliage d'alumine et de zircone.

6. Conditionnement hermétiquement scellé selon la revendication 1, dans lequel ladite seconde extrémité (15, 19) de ladite trace métallique est biocompatible.

7. Conditionnement hermétiquement scellé selon la revendication 6, dans lequel ladite seconde extrémité (15, 19) de ladite trace métallique est du platine.

8. Conditionnement hermétiquement scellé selon la revendication 1, dans lequel au moins un desdits chemins électriquement conducteurs est constitué de :

une pluralité de traces métalliques (74', 74") ayant des première et seconde extrémités, comprenant au moins une trace la plus à l'intérieur (74') la plus proche dudit substrat semi-conducteur (52) et une trace la plus à l'extérieur (74") la plus éloignée dudit substrat semi-conducteur, chaque paire adjacente de traces métalliques étant séparée par un matériau isolant (56') enserré au milieu de manière à former un joint hermétique entre lesdites traces métalliques ;
au moins une traversée d'interconnexion entourée dudit matériau isolant (56') pour interconnecter lesdites paires adjacentes de traces métalliques ;
au moins une traversée la plus à l'intérieur pour interconnecter ladite trace la plus à l'intérieur (74') à au moins un desdits disques (72) sur ledit circuit intégré (70) aux premières extrémités des chemins ;
un matériau isolant pour encapsuler ladite pluralité de traces métalliques, ledit circuit intégré et ledit substrat semi-conducteur, dans lequel la seconde extrémité (19) d'au moins une trace métallique la plus à l'extérieur (74") est au moins partiellement exposée à travers le matériau isolant d'encapsulation (56) au niveau de la seconde extrémité des chemins pour une communication externe ; et dans lequel
ladite combinaison de traces métalliques, de matériau isolant enserré, de matériau d'encapsulation et de traversées assure une voie de communication hermétique jusqu'audit circuit intégré à partir d'un emplacement extérieur audit conditionnement implantable.

9. Conditionnement hermétiquement scellé selon la revendication 1, dans lequel ledit circuit intégré (70) est formé sur une première surface du substrat semi-

conducteur (52) et lesdits chemins électriques (74 ; 74', 74") à partir dudit circuit intégré s'étendent vers l'extérieur de ladite première surface.

10. Conditionnement hermétiquement scellé selon la revendication 9, dans lequel ledit substrat semi-conducteur a une seconde surface sur un côté opposé à ladite première surface dudit substrat et ladite seconde surface dudit substrat est formée sans chemin électrique ou circuit intégré.

11. Procédé de formation d'une connexion hermétique électriquement conductrice à un circuit intégré hermétiquement scellé, ledit procédé comprenant les étapes de :

former un circuit intégré (70) sur une surface d'un substrat semi-conducteur (52), ledit circuit intégré (70) ayant un ou plusieurs disques électriquement conducteurs (72 ; 72a, 72b) pour communiquer et/ou fournir de l'énergie audit circuit intégré ;
former un ou plusieurs chemins électriques (74 ; 74', 74") pour assurer une connexion électrique hermétique audit ou auxdits disques électriquement conducteurs (72 ; 72a, 72b), lesdits chemins ayant des premières extrémités couplées audit ou auxdits disques et des secondes extrémités (13, 15, 17, 19) exposées pour une connexion électrique externe à partir dudit circuit intégré scellé (70) ; et
revêtir et encapsuler ledit substrat semi-conducteur et ledit circuit intégré sauf pour des parties sélectionnées desdites secondes extrémités desdits chemins électriques à l'aide d'un matériau de revêtement isolant (56 ; 56', 56"), ledit circuit hermétiquement scellé étant ainsi adapté pour une implantation dans un tissu vivant ;

dans lequel l'étape de formation d'un ou plusieurs chemins électriques comprend au moins en partie les étapes de :

former une première traversée électriquement conductrice, électriquement couplée à l'un desdits disques (72a, 72b) ;
former une trace métallique (74) orientée sensiblement parallèle à la surface du substrat semi-conducteur (52) sur laquelle le circuit intégré (70) est formé, et électriquement couplée audit ou auxdits disques au niveau de ladite première extrémité par ladite première traversée (72a, 72b) et exposée sur ladite seconde extrémité (15, 19) dudit chemin ; et
entourer ledit chemin électrique du matériau de revêtement isolant (56).

12. Procédé selon la revendication 11, dans lequel lesdits chemins sont formés à partir d'un matériau électriquement conducteur ayant une épaisseur suffisante pour empêcher une fuite due à une quelconque non-uniformité du matériau conducteur.

13. Procédé selon la revendication 11 ou 12, dans lequel l'étape de formation d'un ou plusieurs chemins électriques comprend l'étape de former lesdits chemins électriques (74 ; 74', 74") à partir de platine de sorte que lesdits chemins électriques sont biocompatibles.

14. Procédé selon la revendication 13, dans lequel l'étape de formation desdits chemins électriques à partir de platine comprend de déposer ledit platine en utilisant un dépôt par faisceau ionique pour assurer une uniformité suffisante.

15. Procédé selon la revendication 13, dans lequel l'étape de formation desdits chemins électriques à partir de platine comprend de déposer une couche de platine d'au moins 5 microns pour amener lesdits chemins électriques de platine (74 ; 74', 74") à être hermétiques.

16. Procédé selon la revendication 11, dans lequel l'étape consistant à entourer ledit chemin électrique comprend de déposer de l'alumine pour entourer ledit chemin électrique (74).

17. Procédé selon la revendication 11, dans lequel l'étape de formation d'une seconde traversée électriquement couplée comprend former ladite seconde traversée à partir d'un matériau biocompatible.

18. Procédé selon la revendication 11, dans lequel l'étape de formation d'une seconde traversée électriquement couplée comprend former ladite seconde traversée à partir de platine de sorte que ladite seconde traversée est biocompatible.

19. Procédé selon la revendication 11, dans lequel l'étape de formation d'un ou plusieurs chemins électriques comprend au moins en partie les étapes de :

former une pluralité de traces métalliques (74', 74") ayant des première et seconde extrémités, comprenant au moins une trace la plus à l'intérieur (74') la plus proche dudit substrat semiconducteur (52) et une trace la plus à l'extérieur (74") la plus éloignée dudit substrat semi-conducteur, chaque paire adjacente de traces métalliques (74', 74") étant séparée par un matériau isolant (56') enserré au milieu de manière à former un joint hermétique entre lesdites traces métalliques ;
former au moins une traversée d'interconnexion entourée dudit matériau isolant (56') pour inter-

connecter lesdites paires adjacentes de traces métalliques ;
former au moins une traversée la plus à l'intérieur pour interconnecter ladite trace la plus à l'intérieur (74') à au moins un desdits disques sur ledit circuit intégré aux premières extrémités des chemins ;
déposer un matériau isolant (56) pour encapsuler ladite pluralité de traces métalliques (74', 74"), ledit circuit intégré (70) et ledit substrat semi-conducteur (52) ;
permettre à au moins une partie de ladite seconde extrémité (19) d'une trace métallique la plus à l'extérieur (74") d'être partiellement exposée extérieurement à travers le matériau isolant d'encapsulation (56) au niveau des secondes extrémités des chemins pour une communication externe ; et dans lequel
ladite combinaison de traces métalliques, de matériau isolant enserré, de matériau d'encapsulation et de traversées assure une voie de communication hermétique avec ledit circuit intégré à partir d'un emplacement extérieur audit conditionnement implantable.

20. Procédé selon la revendication 19 comprenant de plus l'étape d'arrondir au moins un coin dudit circuit intégré encapsulé.

21. Procédé selon la revendication 20 dans lequel ladite étape d'arrondi comprend un décapage au sable.

22. Procédé selon la revendication 20 dans lequel l'étape d'arrondi comprend une gravure à l'acide.

23. Conditionnement hermétiquement scellé selon l'une quelconque des revendications 1 à 10, sans couvercle ou capot pour le substrat encapsulé.

24. Procédé selon l'une quelconque des revendications 11 à 22, sans fourniture d'un couvercle ou d'un capot pour le substrat encapsulé.

25. Procédé selon l'une quelconque des revendications 11 à 22, dans lequel l'étape d'encapsulation dudit substrat semi-conducteur et dudit circuit intégré comprend la réalisation d'un dépôt par faisceau ionique du matériau de revêtement isolant.

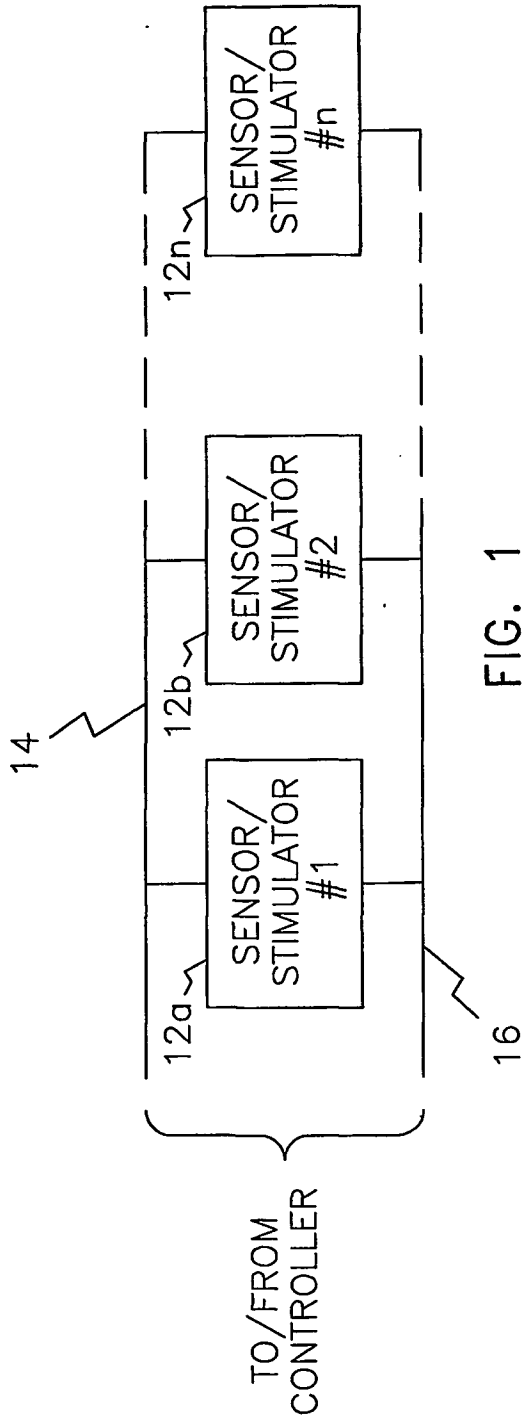
SENSOR/
STIMULATOR
#1
SENSOR/
STIMULATOR
#2
SENSOR/
STIMULATOR
#n
12a
12b
12n
14
16
TO/FROM
CONTROLLER

FIG. 1

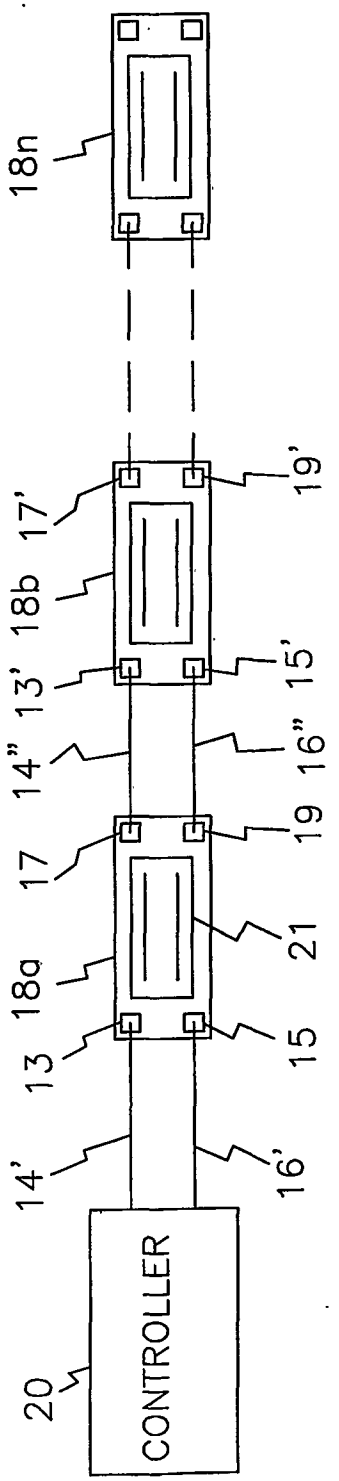
18n
17'
19'
18b
13'
15'
14"
16"
17
19
21
18a
13
15
14'
16'
20
CONTROLLER

FIG. 2

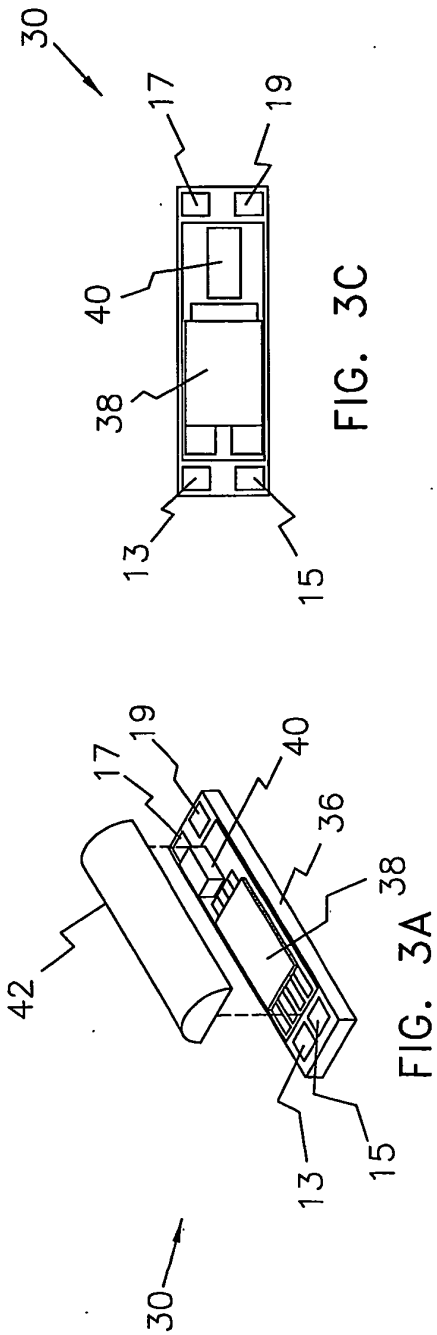

FIG. 3A

FIG. 3C

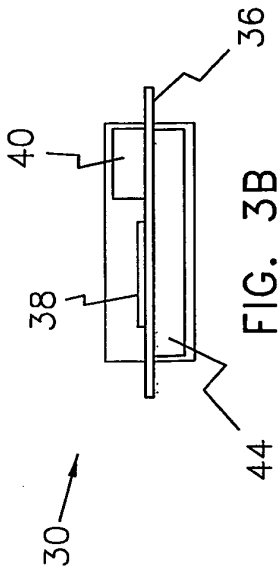

FIG. 3B

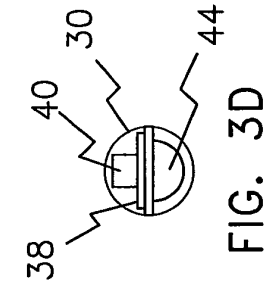

FIG. 3D

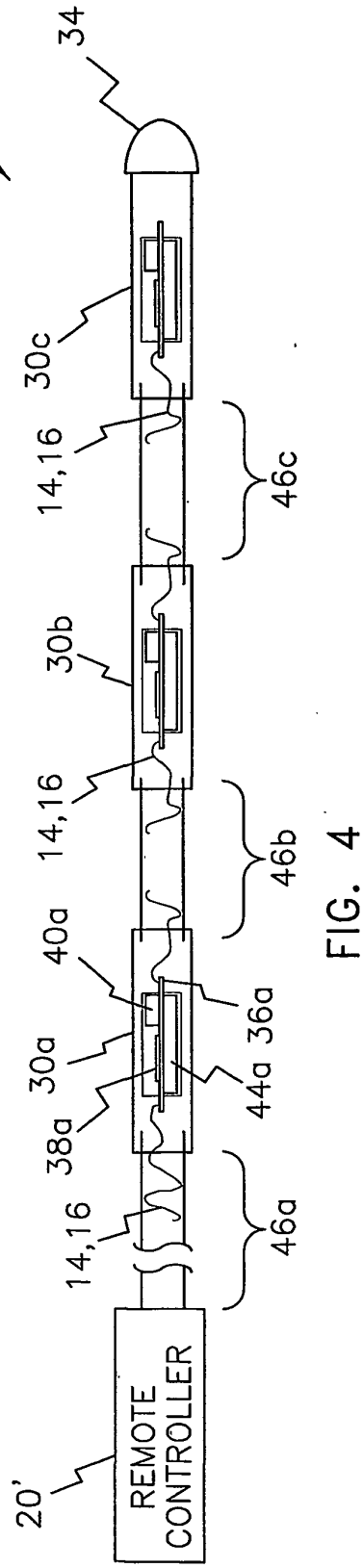

FIG. 4

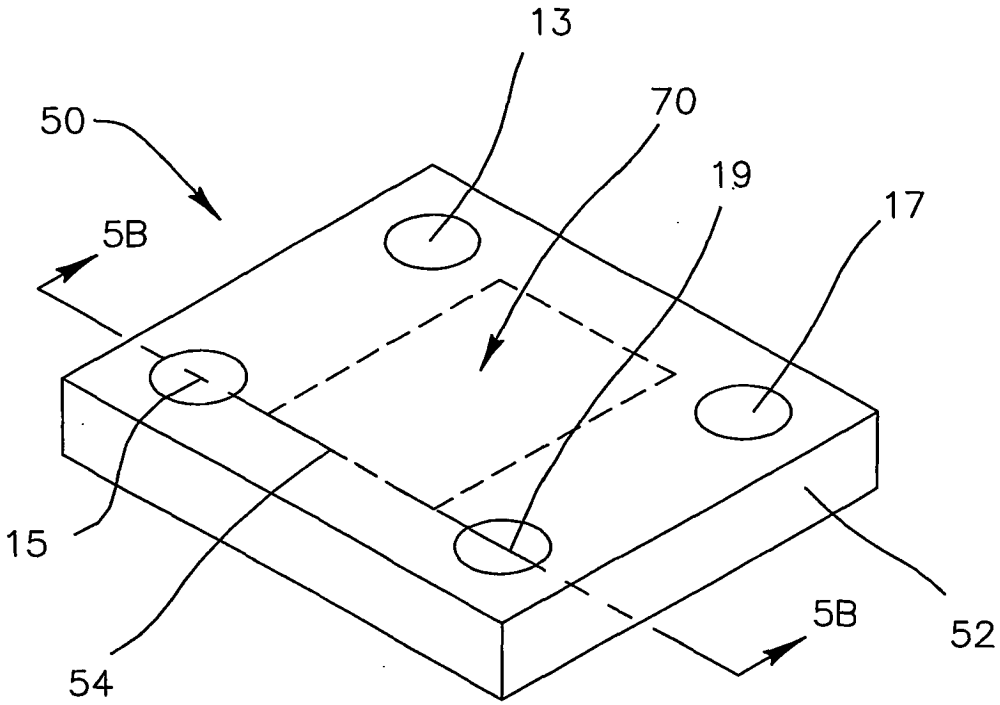

FIG. 5A

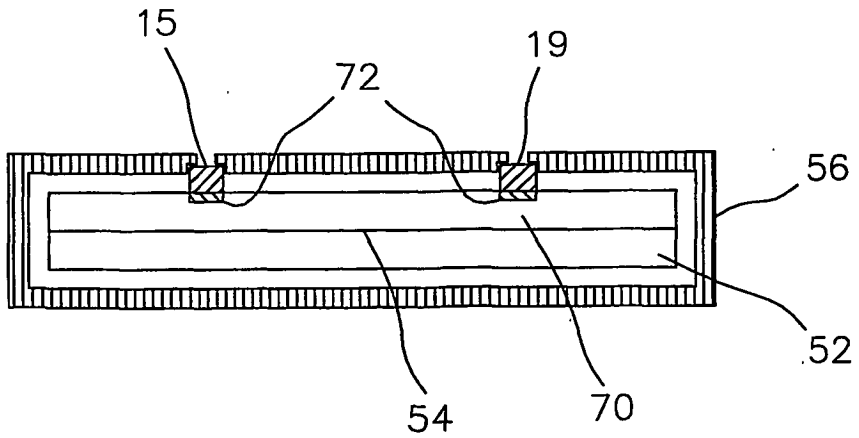

FIG. 5B

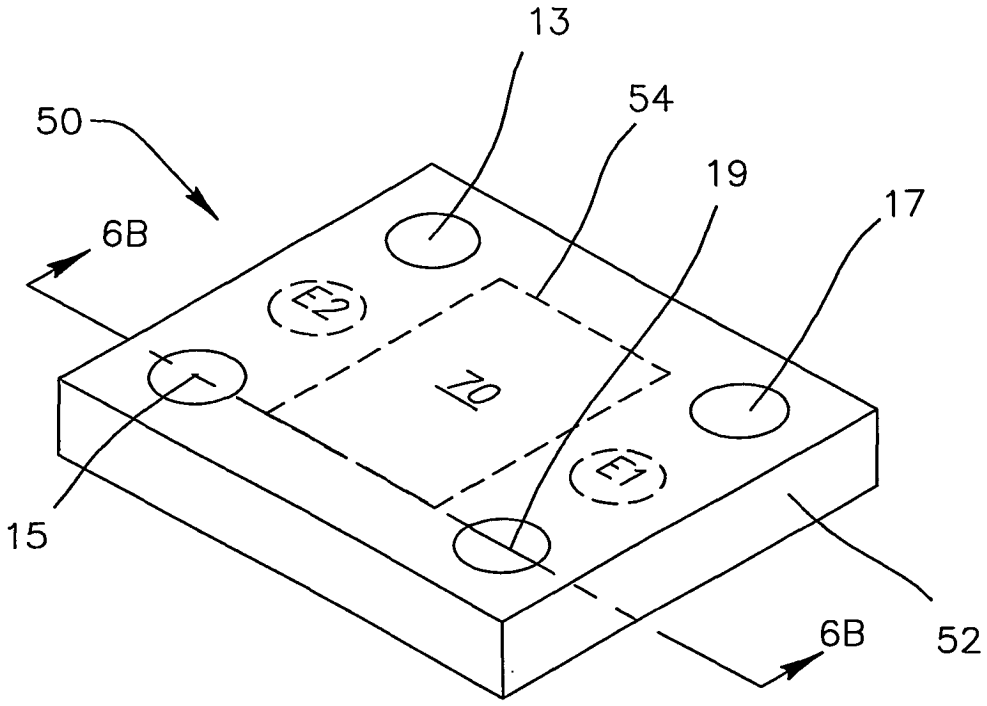
13
54
50
19
17
6B
E2
70
E1
15
6B
52

FIG. 6A

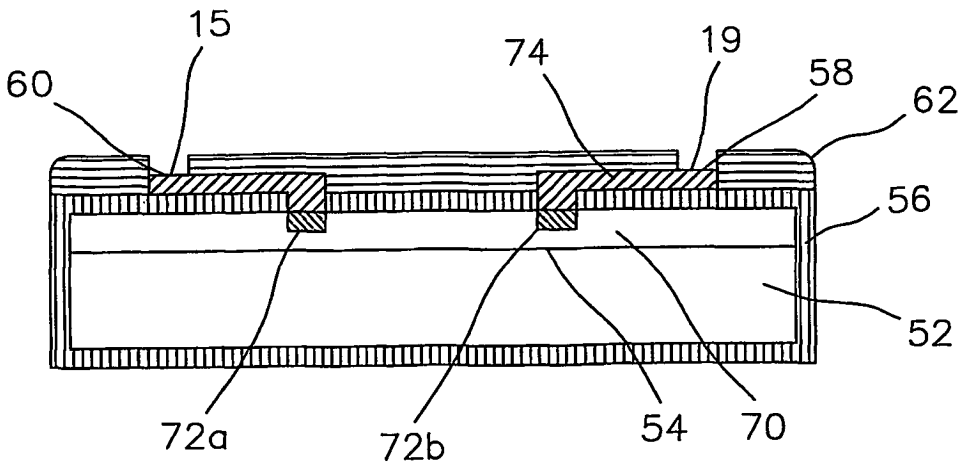
15
74
19
60
58
62
56
52
72a
72b
54
70

FIG. 6B

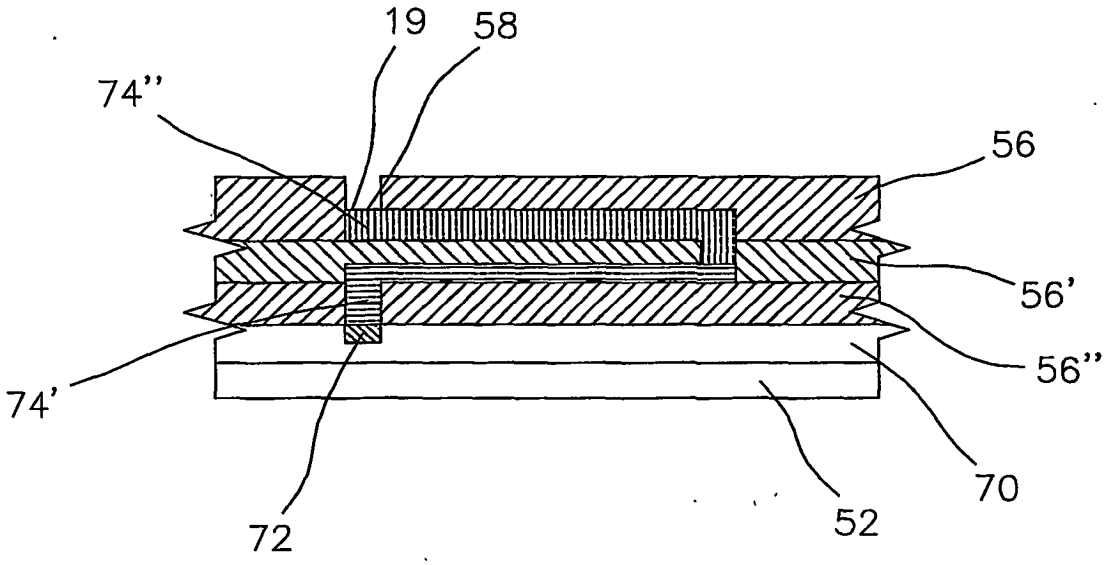

FIG. 7

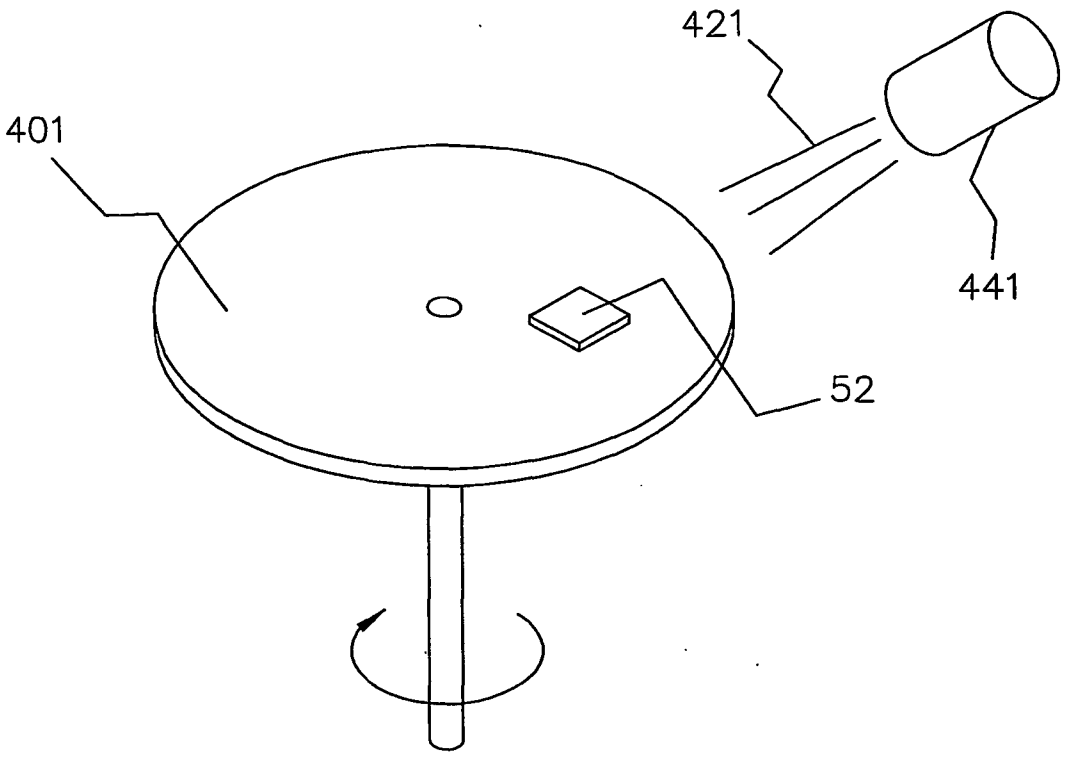

FIG. 8

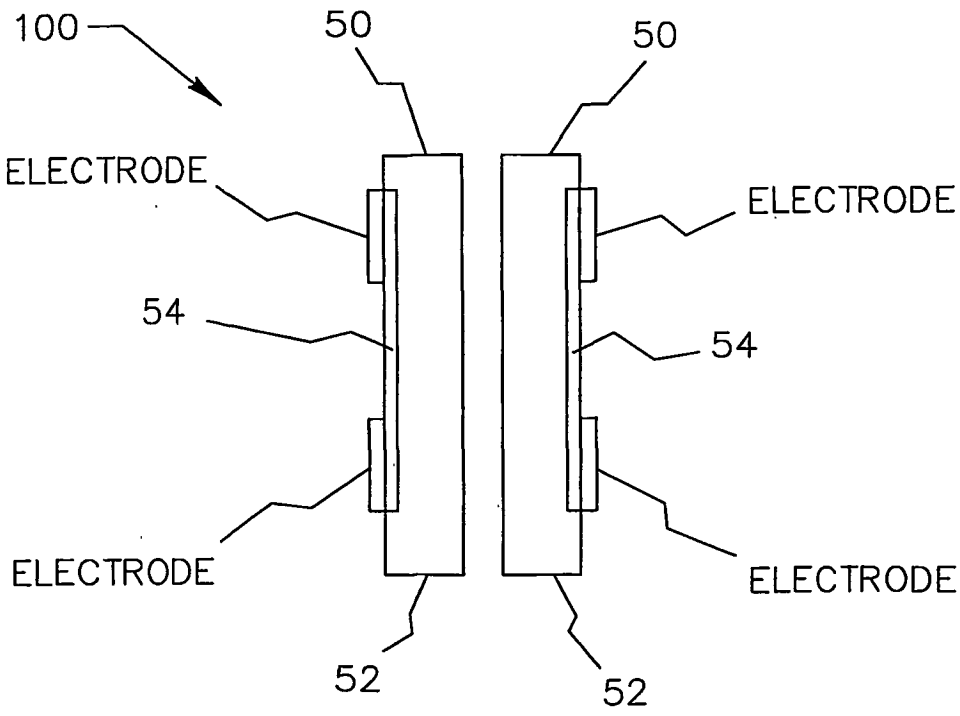
100
50
50
ELECTRODE
ELECTRODE
54
54
ELECTRODE
ELECTRODE
52
52

FIG. 9

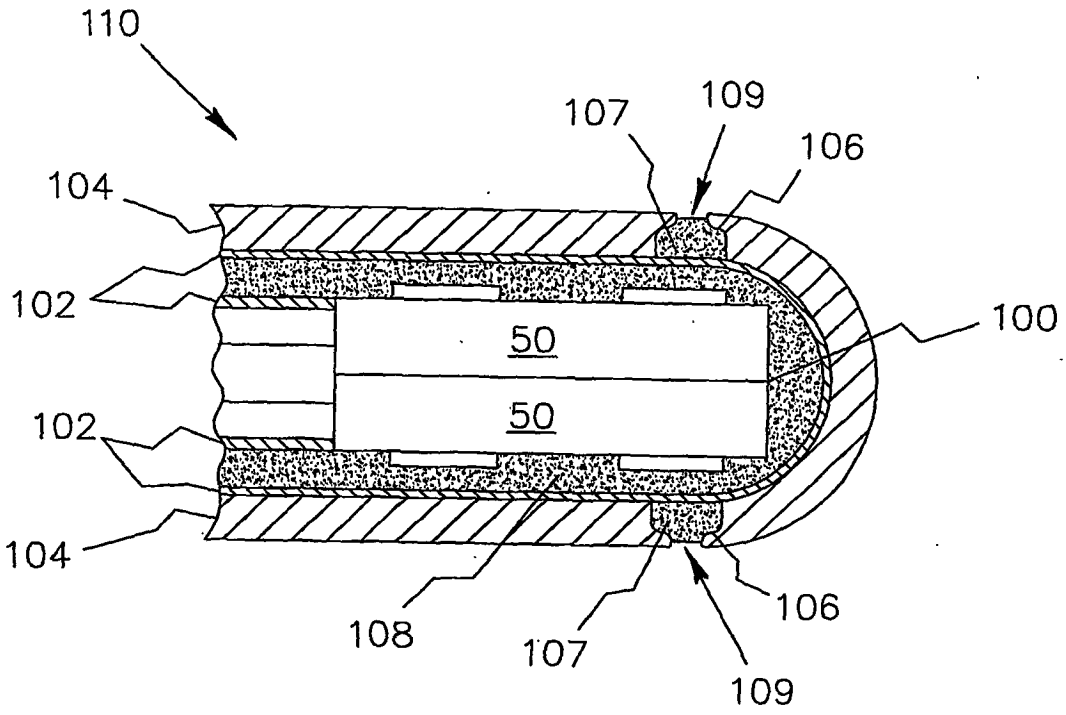

FIG. 10

REFERENCES CITED IN THE DESCRIPTION

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Patent documents cited in the description

- US 5660163 A **[0003]**
- US 6081736 A **[0004]**
- US 6119028 A **[0004]**
- US 5999848 A **[0004] [0037]**
- US 5782891 A **[0014]**
- US 5833603 A **[0015]**
- US 6043437 A **[0016] [0033] [0046]**
- US 5750926 A **[0029]**
- US 5497772 A **[0030] [0032]**
- US 4474827 A **[0042]**
- US 5508368 A **[0042]**

专利名称(译)	用于可植入设备的密封穿通件		
公开(公告)号	EP1408863B1	公开(公告)日	2010-10-13
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申请(专利权)人(译)	艾尔弗雷德·E·曼基金会为科研		
当前申请(专利权)人(译)	艾尔弗雷德·E·曼基金会为科研		
[标]发明人	SCHULMAN JOSEPH H		
发明人	SCHULMAN, JOSEPH, H.		
IPC分类号	A61B5/1459 A61N1/375 H01L23/31 H01L23/538 H01L29/06 A61B5/145 A61B5/00 A61B5/1473 A61B5/1486 A61M5/172 A61N1/05 A61N1/365 A61N1/372		
CPC分类号	A61B5/0031 A61B5/01 A61B5/145 A61B5/14532 A61B5/14546 A61B5/1473 A61B5/14865 A61B5/4839 A61B2560/0219 A61M2205/0244 A61N1/05 A61N1/3754 H01L23/3107 H01L23/5387 H01L29/0657 H01L2924/0002 H01L2924/19041 H01L2924/00		
优先权	09/882712 2001-06-14 US		
其他公开文献	EP1408863A4 EP1408863A1		
外部链接	Espacenet		

摘要(译)

本发明提供了一种可植入衬底传感器，其包括形成在衬底内或衬底上的电子电路。 然后，保护涂层覆盖基底，形成在涂层下面具有电路的气密密封包装。 电路具有用于向电路通信和/或向电路供电的导电垫。 电气路径可提供与导电焊盘的气密电连接，以便外部连接至密封电路。 在第一实施例中，通路是由生物相容性材料制成的通孔，该生物相容性材料通过增加其厚度或通过离子束沉积而被密封。 替代地，这些路径由金属迹线形成，该金属迹线被生物相容性绝缘材料围绕，该金属迹线基本上平行于基板的表面，该基板的表面通过第一通孔连接到导电垫，并且其第二端可从外部进入密封封装以提供外部电连接。 到内部的密封电路。

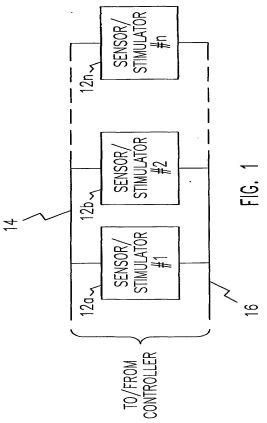

FIG. 1

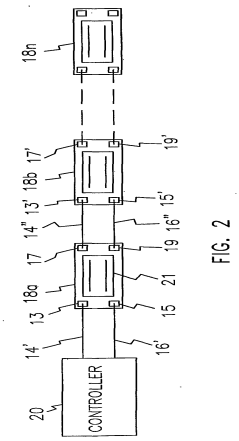

FIG. 2